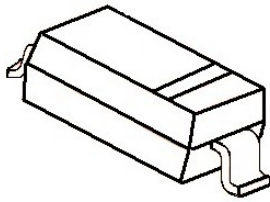


SOD-123

特征 Features

- 齐纳击穿阻抗低; Low Zener Impedance
- 最大功率耗散 500mW; Power Dissipation of 500mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
功率消耗 Power Dissipation	Pd	500 ¹⁾	mW
正向压降 Forward Voltage @IF=10mA	Vf	0.9 ²⁾	V
存储温度 Storage temperature range	Ts	-65-+150	°C

 1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm²

2) Short duration test pulse used to minimize self-heating effect

3) f=1KHz

电特性 (TA = 25°C 除非另有规定)

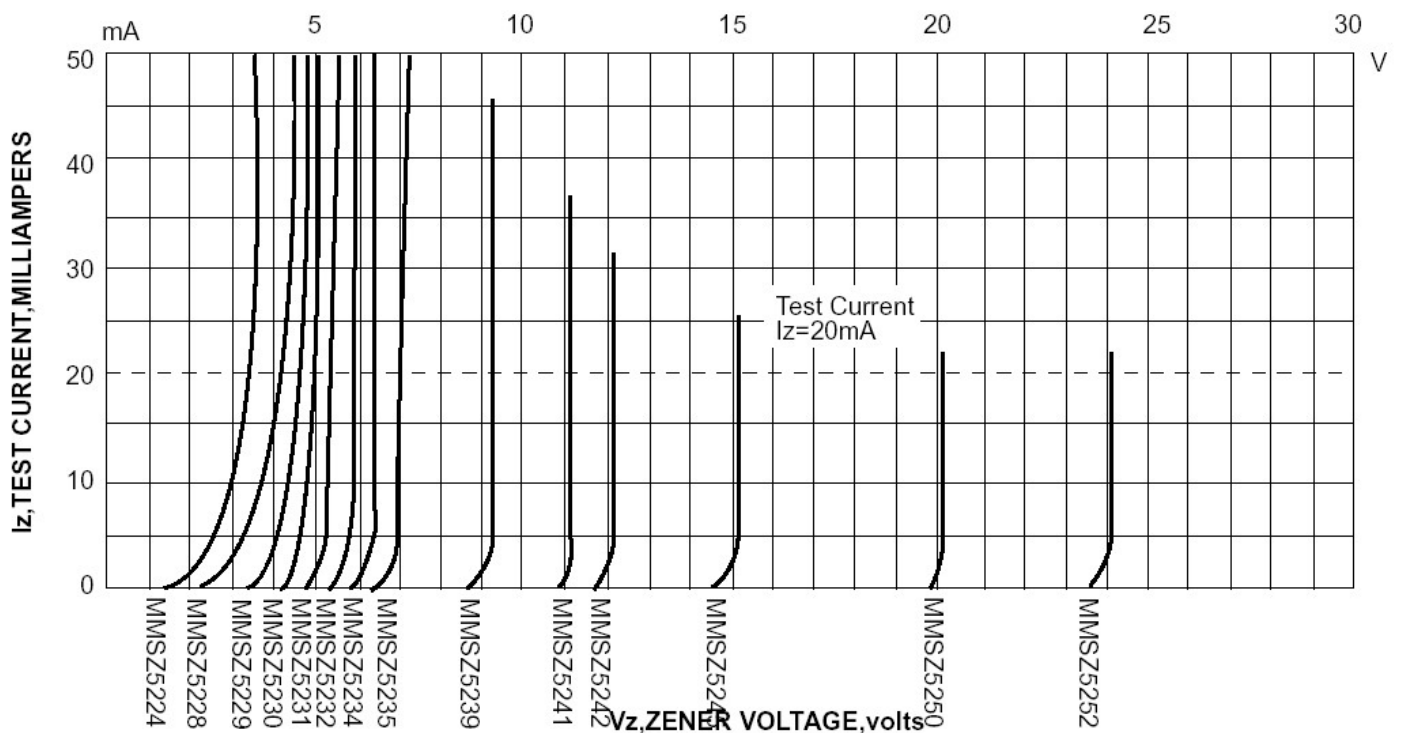
Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

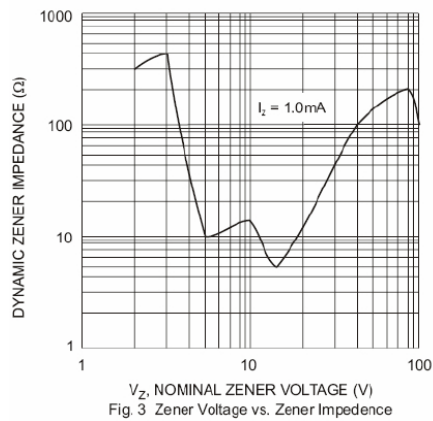
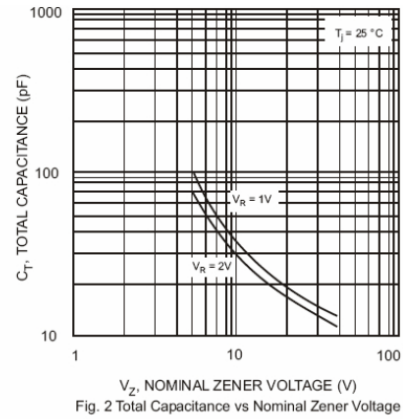
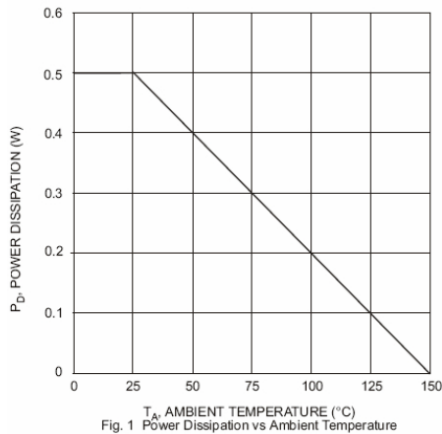
型号	印字 (代码)	Vz1(@Izt)			Zzt@Izt	Zzk		IR	
		Min (V)	Max (V)	Izt mA	Max Ω	Max Ω	Izk mA	Max uA	VR V
MM1Z5221B	A4	2.28	2.52	20	30	1200	0.25	100	1.0
MM1Z5223B	B4	2.57	2.84	20	30	1300	0.25	75	1.0
MM1Z5225B	C4	2.85	3.15	20	30	1600	0.25	50	1.0
MM1Z5226B	D4	3.14	3.47	20	28	1600	0.25	25	1.0
MM1Z5227B	E4	3.42	3.78	20	24	1700	0.25	15	1.0
MM1Z5228B	F4	3.71	4.10	20	23	1900	0.25	10	1.0
MM1Z5229B	H4	4.09	4.52	20	22	2000	0.25	5.0	1.0
MM1Z5230B	J4	4.47	4.94	20	19	1900	0.25	5.0	2.0
MM1Z5231B	K4	4.85	5.36	20	17	1600	0.25	5.0	2.0
MM1Z5232B	M4	5.32	5.88	20	11	1600	0.25	5.0	3.0
MM1Z5234B	N4	5.89	6.51	20	7	1000	0.25	5.0	4.0
MM1Z5235B	P4	6.46	7.14	20	5	750	0.25	3	5.0
MM1Z5236B	R4	7.13	7.88	20	6	500	0.25	3	6.0
MM1Z5237B	X4	7.79	8.61	20	8	500	0.25	3	6.5
MM1Z5239B	Y4	8.65	9.56	20	10	600	0.25	3	7.0
MM1Z5240B	Z4	9.50	10.50	20	17	600	0.25	3	8.0
MM1Z5241B	A5	10.45	11.55	20	22	600	0.25	2.0	8.4
MM1Z5242B	B5	11.40	12.60	20	30	600	0.25	1.0	9.1

型号	印字 (代码)	Vz1(@Izt)			Zzt@Izt	Zzk		IR	
		Min (V)	Max (V)	Izt mA	Max Ω	Max Ω	Izk mA	Max uA	VR V
MM1Z5243B	C5	12.35	13.65	9.5	13	600	0.25	0.5	9.9
MM1Z5245B	D5	14.25	15.75	8.5	16	600	0.25	0.1	11
MM1Z5246B	E5	15.20	16.80	7.8	17	600	0.25	0.1	12
MM1Z5248B	F5	17.10	18.90	7.0	21	600	0.25	0.1	14
MM1Z5249B	F9	18.05	19.95	6.6	23	600	0.25	0.1	14
MM1Z5250B	H5	19.00	21.00	6.2	25	600	0.25	0.1	15
MM1Z5251B	J5	20.90	23.10	5.6	29	600	0.25	0.1	17
MM1Z5252B	K5	22.80	25.20	5.2	33	600	0.25	0.1	18
MM1Z5253B	M9	23.75	26.25	5.0	35	600	0.25	0.1	19
MM1Z5254B	M5	25.65	28.35	4.6	41	600	0.25	0.1	21
MM1Z5256B	N5	28.50	31.50	4.2	49	600	0.25	0.1	23
MM1Z5257B	P5	31.35	34.65	3.8	58	700	0.25	0.1	25
MM1Z5258B	R5	34.20	37.80	3.4	70	700	0.25	0.1	27
MM1Z5259B	X5	37.05	40.95	3.2	80	800	0.25	0.1	30
MM1Z5260B	Y5	40.85	45.15	3.0	93	900	0.25	0.1	33
MM1Z5261B	Z5	44.65	49.35	2.7	105	1000	0.25	0.1	36
MM1Z5262B	A6	48.45	53.55	2.5	125	1100	0.25	0.1	39
MM1Z5263B	B6	53.20	58.80	2.2	150	1300	0.25	0.1	43
MM1Z5265B	C6	58.90	65.10	2.0	185	1400	0.25	0.1	47
MM1Z5266B	D6	64.60	71.40	1.8	230	1600	0.25	0.1	52
MM1Z5267B	E6	71.25	78.75	1.7	270	1700	0.25	0.1	56

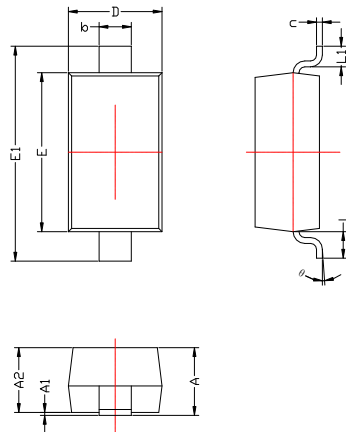
VF≤0.9V@IF=10mA

Breakdown characteristics





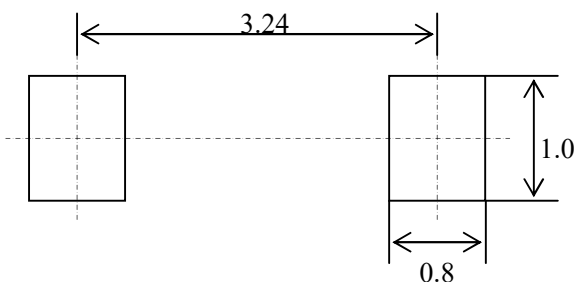
SOD-123 PACKAGE OUTLINE Plastic surface mounted package



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考 Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



中心距: 3.24
脚宽: 0.55
焊盘宽: 1.00
脚长: 0.50
焊盘长: 0.80

技术要求:

- 1, 塑封体尺寸: 2.70 X 1.60
- 2: 未注公差为: ±0.05
- 3, 所有单位: mm

